In the Claims

1. (Currently amended) A method for removing contaminate particulate matter from a contaminate particle containing integrated circuit semiconductor substrate surface comprising the steps of:

applying a sacrificial coating of a ~~material~~ curable polymer to ~~a~~ an integrated circuit semiconductor substrate surface containing undesirable particulate matter thereon, which curable polymer ~~material~~ is to encapsulate and suspend the undesirable particles therein;

fluidizing the ~~material~~ curable polymer if necessary;

applying energy to the coated substrate to dislodge at least some of the particulate matter from the surface of the integrated circuit semiconductor substrate into the fluid curable polymer sacrificial coating such that the particulate matter is partially or fully encapsulated and suspended within the curable polymer sacrificial coating forming a particulate matter containing curable polymer sacrificial ~~material~~ coating;

~~forming~~ curing the fluidized particulate matter containing curable polymer sacrificial ~~material~~ coating to form a cured polymer ~~into a~~ strippable film; and

removing the particulate matter containing cured polymer sacrificial ~~material coating~~ strippable film from the substrate surface as a strippable film providing a substrate surface having less particulate matter thereon.

2. (original) The method of claim 1 wherein the substrate is a semiconductor wafer.

3. (Currently amended) The method of claim 1 wherein the sacrificial coating ~~material~~ curable polymer is a fluid.

4. (original) The method of claim 1 wherein the energy used is sonic energy.

5. (original) The method of claim 1 wherein the energy used is thermal, centrifugal, magnetic or vibrational.

6. (Currently amended) The method of claim 1 wherein the sacrificial coating ~~material~~ curable polymer is a liquid.

7. (canceled)

8.-9. (canceled)

10. (canceled)

11.-25. (Canceled)

26. (Currently amended) The method of claim 1 wherein the cured polymer strippable film is formed simultaneously with application of the energy to dislodge the particles.